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PATENT APPLN. NO. 10/552,663 RESPONSE UNDER 37 C.F.R. §1.111 PATENT NON-FINAL

IN THE CLAIMS:

1. (currently amended) A low dielectric constant polymer, comprising monomeric units derived from a compound having the general formula I

$$(R^1-R^2)_n-Si-(X^1)_{4-n},$$

wherein

each x^1 is independently selected from hydrogen and inorganic leaving groups,

 \mathbb{R}^2 is an optional group and comprises an alkylene having 1 to 6 carbon atoms or an arylene,

R¹ is a polycycloalkyl group adamantyl or diadamantyl substituted with 1 to 3 alkyl substitutents, which optionally carry 1 to 6 halogen substituents, and n is an integer 1 to 3.

2. (currently amended) The polymer according to claim 1, wherein the organic content of the polymer is in the range of 30 to 70 wt.-%, preferably higher than 48 wt %.

3 - 6. (canceled)

- 7. (previously presented) The polymer according to claim 1, wherein the inorganic leaving group is selected from halogens.
- 8. (previously presented) The polymer according to claim 1, obtainable by homopolymerization of compounds of the formula I.
- 9. (currently amended) The polymer according to claim 1 A low dielectric constant polymer, comprising monomeric units derived from a compound having the general formula I

$$\frac{(R^{1}-R^{2})_{n}-Si-(X^{3})_{4-n}}{I}$$

wherein

each X¹ is independently selected from hydrogen and inorganic leaving groups,

R² is an optional group and comprises an alkylene having 1 to 6 carbon atoms or an arylene.

R1 is a polycycloalkyl group, and

n is an integer 1 to 3, which is obtainable by copolymerization of a compound of formula I with a compound of formula II

$$(R^3-R^4)_n-Si-(X^2)_{4-n},$$
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wherein

X² is hydrogen or a hydrolysable group selected from halogen, acyloxy, alkoxy and OH groups,

R4 is an optional group and comprises an alkylene having 1 to 6 carbon atoms or an arylene and

R³ is an alkyl having 1 to 16 carbon atoms, a vinyl having from 2 to 16 carbon atoms, a cycloalkyl having from 3 to 16 carbon atoms, an aryl having from 5 to 18 carbon atoms or a polycyclic alkyl group having from 7 to 16 carbon atoms, and n is an integer 1-3.

- 10. (original) The polymer according to claim 9, wherein R³ is selected from alkyl groups having 1 to 6 carbon atoms, vinyl groups having from 2 to 6 carbon atoms, and aryl groups having 6 carbon atoms.
- 11. (previously presented) The polymer according to claim 9, wherein the molar ratio between monomeric units derived from compounds according to formula I and of formula II is in the range of 25:75 to 75:25.

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- 12. (previously presented) The polymer according to claim 9, wherein \mathbb{R}^1 or \mathbb{R}^3 , respectively, is directly bonded to the silicon atom.
- 13. (previously presented) The polymer according to claim 9, wherein R¹ or R³, respectively, is bonded to the silicon atom via an alkylene chain selected from methylene, ethylene and propylene, or an arylene group selected from phenylene.
- 14. (currently amended) The polymer according the claim 1, wherein the total sum dielectric components at 1 MHz is 2.50 or less, preferably 2.1 or less.
- 15. (original) The polymer according to claim 14, wherein the orientational dielectric constant of the polymer is 0.4 or less.
- 16. (previously presented) The polymer according to claim 1, wherein the oxygen content of the polymer is less than 15 atomic %.
- 17. (previously presented) The polymer according to claim 9, wherein the carbon content of the polymer is more than 25 atomic %.

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- 18. (currently amended) The polymer according to claim 1, wherein the dielectric constant of the dielectric material after curing is 2.50 or less, preferably 2.30 or less.
- 19. (currently amended) The polymer according to claim 1, wherein the porosity of the dielectric material is less than 20 %, preferably less than 15 %.
- 20. (original) The polymer according to claim 1, wherein the average pore radius is less than 1 nm.
- 21. (currently amended) The polymer according to claim 1, wherein the Young's modulus of the film is higher than 4 GPa after curing, in particular higher than 6 GPa.

22 - 53. (canceled)

- 54. (new) The polymer according to claim 2, wherein the organic content of the polymer is greater than 48 wt-%.
- 55. (new) The polymer according the claim 14, wherein the total sum dielectric components at 1 MHz is 2.10 or less.

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- 56. (new) The polymer according to claim 18, wherein the dielectric constant of the dielectric material after curing is 2.30 or less.
- 57. (new) The polymer according to claim 19, wherein the porosity of the dielectric material is less than 15 %.
- 58. (new) The polymer according to claim 21, wherein the Young's modulus of the film is higher than 6 GPa after curing.